TE Internal #: 1-2379397-1

Internal I/O Connectors, Mini Cool Edge I/O (MCIO), Cable Plug Assembly, Vertical, Cable-to-Board, SFF-TA-1016, 74 Position,

Surface Mount

View on TE.com >



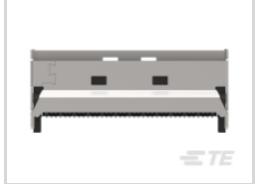
#### Connectors > PCB Connectors > Internal I/O Connectors











Internal I/O Connector Type: Mini Cool Edge I/O (MCIO)

Connector Mates With: Cable Plug Assembly

PCB Mount Orientation: Vertical
Connector System: Cable-to-Board
Industry Standard: SFF-TA-1016

## **Features**

# Product Type Features

Internal I/O Connector Type	Mini Cool Edge I/O (MCIO)
Connector Mates With	Cable Plug Assembly
Connector System	Cable-to-Board
Connector & Contact Terminates To	Printed Circuit Board

# **Configuration Features**

Number of Rows	2
PCB Mount Orientation	Vertical
Number of Positions	74

## **Contact Features**

Contact Mating Area Plating Material	Gold
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Copper Alloy
Contact Current Rating (Max)	1.1 A



Contact Mating Area Plating Material Thickness	.381 μm[15 μin]
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#### **Termination Features**

Termination Method to Printed Circuit Board	Surface Mount
Mechanical Attachment	
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	.6 mm[.023 in]
Usage Conditions	
Operating Temperature Range	-55 – 85 °C[-67 – 185 °F]

## Operation/Application

C	Circuit Application	Signal

## **Industry Standards**

Industry Standard	SFF-TA-1016

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides



on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts









# Customers Also Bought















# **Documents**

## **Product Drawings**

MCIO INTERGRATED CONN, V/T,8X, SMT TYPE

English

#### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_1-2379397-1\_1.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_1-2379397-1\_1.3d\_igs.zip



English

**Customer View Model** 

ENG\_CVM\_CVM\_1-2379397-1\_1.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

**Product Specifications** 

**Application Specification** 

English